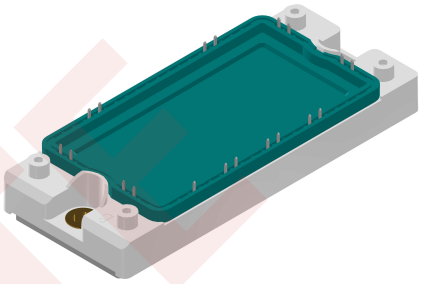
High Voltage Standard Rectifier Module

3~ Rectifier			Brake Chopper		
V_{RRM}	=	2200 V	V_{CES}	=	1700 V
I_{DAV}	=	150 A	I_{C25}	=	113 A
I_{FSM}	=	1100 A	$V_{CE(sat)}$	=	1.9 V

3~ Rectifier Bridge + Brake Unit + NTC

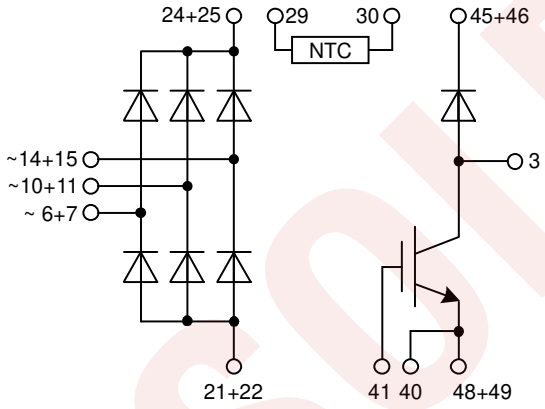
Part number

VUB135-22NO1



Backside: isolated

E72873



Features / Advantages:

- Package with DCB ceramic
- Improved temperature and power cycling
- Planar passivated chips
- Very low forward voltage drop
- Very low leakage current
- NTC

Applications:

- 3~ Rectifier with brake unit for drive inverters

Package: E2-Pack

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: Copper internally DCB isolated
- Advanced power cycling
- Phase Change Material available

Disclaimer Notice

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Rectifier

Symbol	Definition	Conditions		Ratings min.	typ.	max.	Unit
V_{RSM}	*max. non-repetitive reverse blocking voltage*		T_{VJ} = 25°C			2300	V
V_{RRM}	*max. repetitive reverse blocking voltage*		T_{VJ} = 25°C			2200	V
I_R	*reverse current*	V_R = 2200 V	T_{VJ} = 25°C			100	µA
		V_R = 2200 V	T_{VJ} = 150°C			2	mA
V_F	*forward voltage drop*	I_F = 50 A	T_{VJ} = 25°C			1.20	V
		I_F = 150 A				1.68	V
		I_F = 50 A	T_{VJ} = 125°C			1.13	V
		I_F = 150 A				1.74	V
I_{DAV}	*bridge output current*	T_C = 105°C	T_{VJ} = 150°C			150	A
		rectangular d = ⅓					
V_{F0}	*threshold voltage* } *for power loss calculation only*		T_{VJ} = 150°C			0.79	V
r_F	*slope resistance* }					6.4	mΩ
R_{thJC}	*thermal resistance junction to case*					0.5	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.1		K/W
P_{tot}	*total power dissipation*		T_C = 25°C			250	W
I_{FSM}	*max. forward surge current*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			1.10	kA
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.19	kA
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			935	A
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			1.01	kA
I^2t	*value for fusing*	t = 10 ms; (50 Hz), sine	T_{VJ} = 45°C			6.05	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			5.89	kA²s
		t = 10 ms; (50 Hz), sine	T_{VJ} = 150°C			4.37	kA²s
		t = 8,3 ms; (60 Hz), sine	V_R = 0 V			4.25	kA²s
C_J	*junction capacitance*	V_R = 400 V; f = 1 MHz	T_{VJ} = 25°C		37		pF

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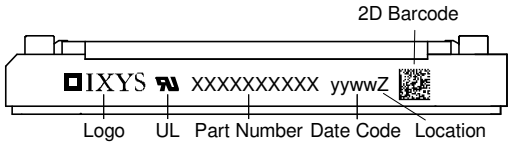
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Brake IGBT + Diode				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1700	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient gate emitter voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			113	A
I_{C80}			T_C = 80°C			80	A
P_{tot}	*total power dissipation*		T_C = 25°C			445	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 75 A; V_{GE} = 15 V	T_{VJ} = 25°C		1.9	2.13	V
			T_{VJ} = 125°C		2.8		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 3 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5.2	5.8	6.4	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.6	mA
			T_{VJ} = 125°C		0.6		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				400	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 900 V; V_{GE} = 15 V; I_C = 75 A			850		nC
$t_{d(on)}$	*turn-on delay time*	inductive load V_{CE} = 900 V; I_C = 75 A V_{GE} = ±15 V; R_G = 18 Ω	T_{VJ} = 125°C		250		ns
t_r	*current rise time*				70		ns
$t_{d(off)}$	*turn-off delay time*				670		ns
t_f	*current fall time*				420		ns
E_{on}	*turn-on energy per pulse*				29		mJ
E_{off}	*turn-off energy per pulse*				17		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 18 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEK} = 1700 V				150	A
SCSOA	*short circuit safe operating area*	V_{CEK} = 1700 V					
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±15	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 18 Ω; non-repetitive			340		A
R_{thJC}	*thermal resistance junction to case*					0.28	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.10		K/W
Brake Diode							
V_{RRM}	*max. repetitive reverse voltage*		T_{VJ} = 25°C			1700	V
I_{F25}	*forward current*		T_C = 25°C			75	A
I_{F80}			T_C = 80°C			50	A
V_F	*forward voltage*	I_F = 60 A	T_{VJ} = 25°C			3.05	V
			T_{VJ} = 125°C		2.20		V
I_R	*reverse current*	V_R = V_{RRM}	T_{VJ} = 25°C			0.1	mA
			T_{VJ} = 125°C			6	mA
Q_{rr}	*reverse recovery charge*	V_R = 900 V $-di_F/dt$ = 1000 A/µs I_F = 60 A; V_{GE} = 0 V	T_{VJ} = 125°C		18		µC
I_{RM}	*max. reverse recovery current*				70		A
t_{rr}	*reverse recovery time*				900		ns
E_{rec}	*reverse recovery energy*				8		mJ
R_{thJC}	*thermal resistance junction to case*					0.65	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.25		K/W

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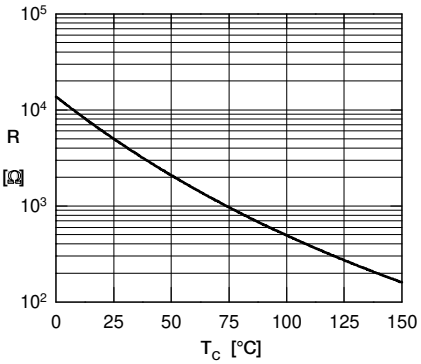
Package E2-Pack				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal				40	A
T_{VJ}	*virtual junction temperature*			-40		150	°C
T_{op}	*operation temperature*			-40		125	°C
T_{stg}	*storage temperature*			-40		125	°C
Weight					176		g
M_D	*mounting torque*			3		6	Nm
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	6.0			mm
$d_{Spb/Apb}$			*terminal to backside*	12.0			mm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; I_{ISOL} ≤ 1 mA	3600			V
		t = 1 minute		3000			V



Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	VUB135-22NO1	VUB135-22NO1	Box	6	503948

Temperature Sensor NTC

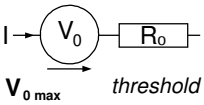
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	*resistance*	T_{VJ} = 25°	4.75	5	5.25	kΩ
$B_{25/50}$	*temperature coefficient*			3375		K



Typ. NTC resistance vs. temperature

Equivalent Circuits for Simulation

** on die level* T_{VJ} = 150°C



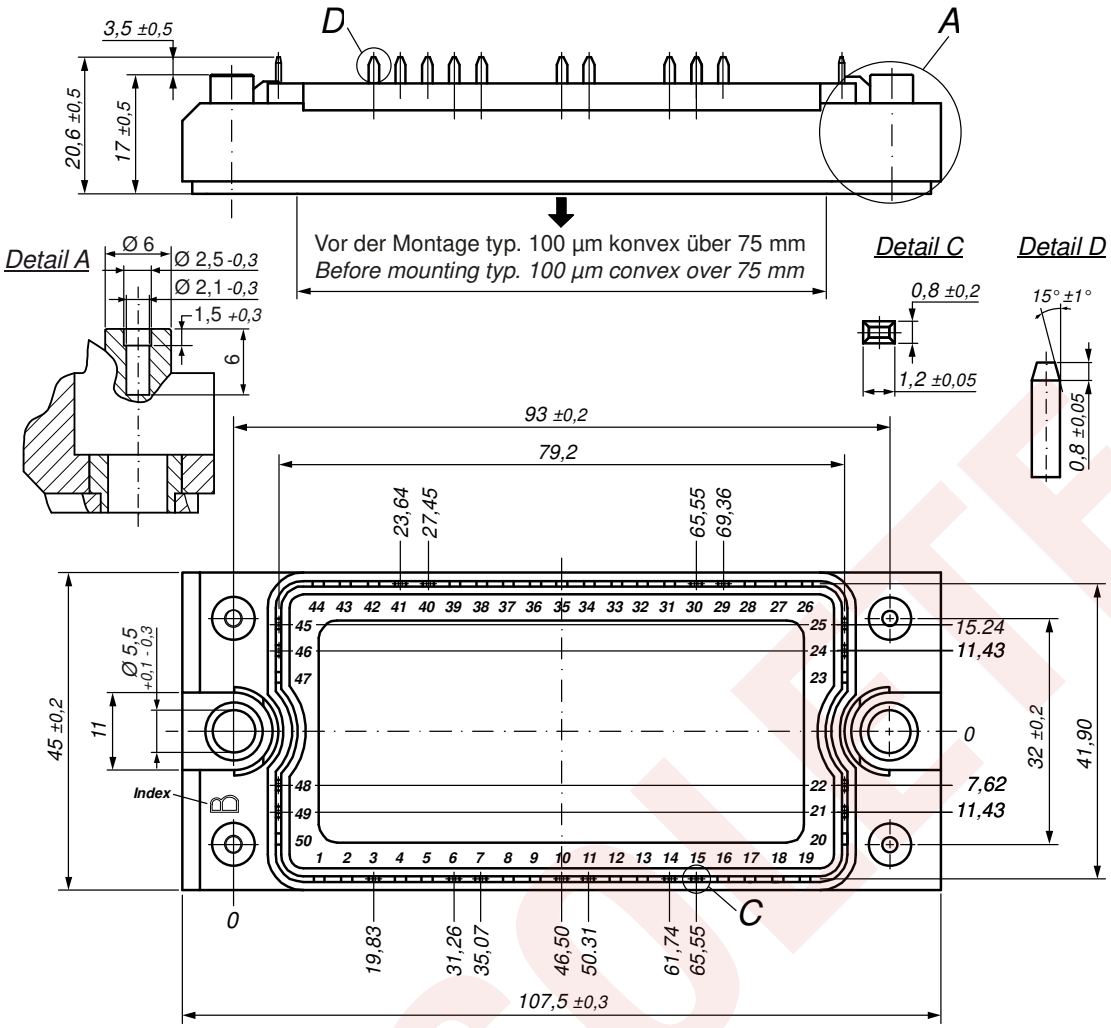
Rectifier

$V_{0\ max}$	*threshold voltage*	0.79	V
$R_{0\ max}$	*slope resistance **	3.3	mΩ

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Outlines E2-Pack

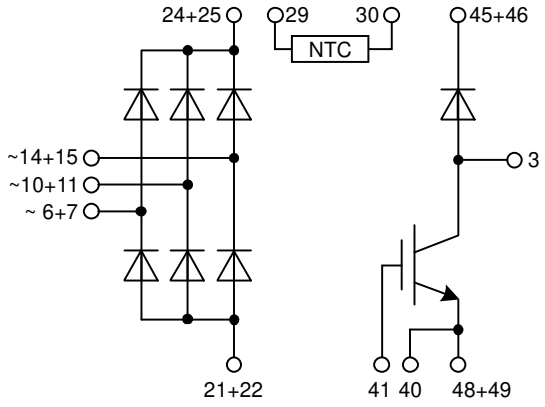


Bemerkung / ***Note:***

- Nichttolerierte Maße nach / *Measure without tolerances according DIN ISO 2768-T1-m*
- PCB-Lochmuster / *PCB hole pattern:* **see pin position**
- Toleranz Pin-Position und PCB-Lochmuster / *Tolerance of pin position and PCB hole pattern:* ⌖ **0.1**
- Montageanleitung / *Mounting instruction:* www.ixys.com **Application note IXAN0024**

***Detail A*:** PCB-Montage / *Mounting on PCB*

- Empfohlene, selbstschneidende Schraube / *Recommended, self-tapping screw:* **EJOT PT®** (Größe / *size:* **K25**)
- Max. Schraubenlänge / *Max. screw length:* **PCB-Dicke** / **thickness + 6 mm** *(*max. Lochtiefe / *hole depth)*
- Empfohlenes Drehmoment / *Recommended mounting torque:* **1.5 Nm**



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Rectifier

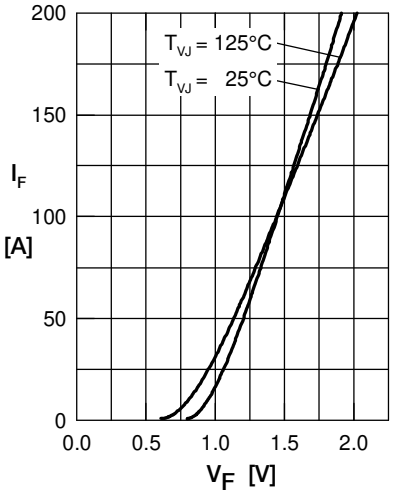


Fig. 1 Forward current vs. voltage drop per diode

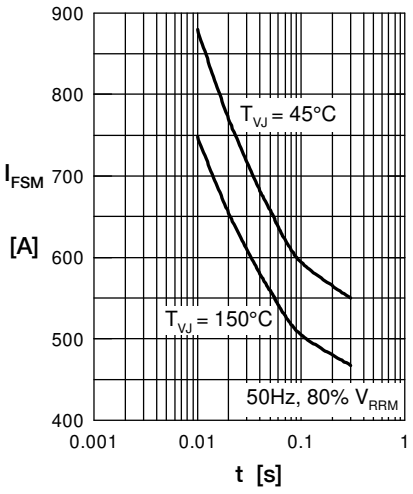


Fig. 2 Surge overload current vs. time per diode

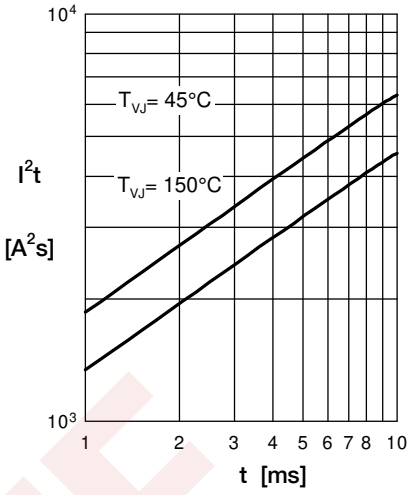


Fig. 3 I^2t vs. time per diode

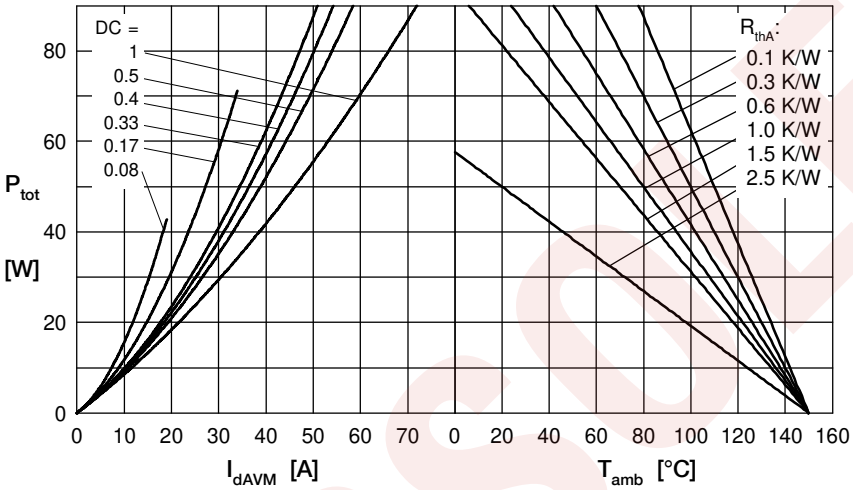


Fig. 4 Power dissipation vs. forward current and ambient temperature per diode

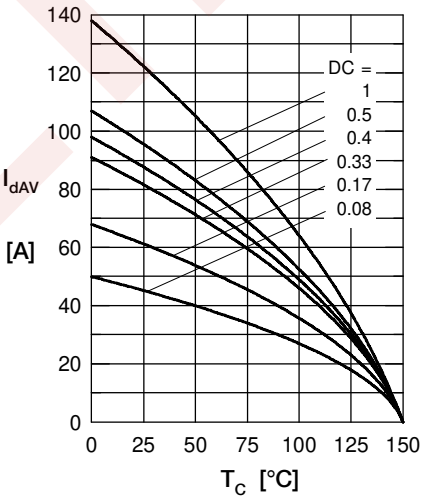


Fig. 5 Max. forward current vs. case temperature per diode

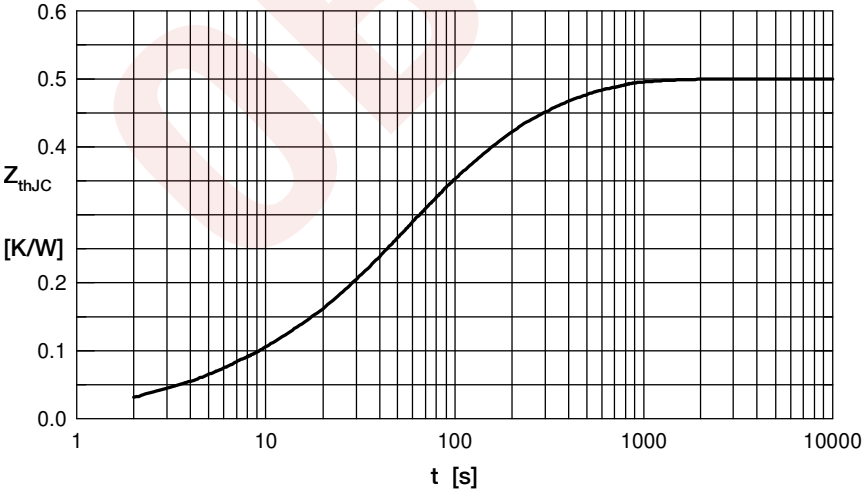


Fig. 6 Transient thermal impedance junction to case vs. time per diode

Constants for Z_{thJC} calculation:

i	R_{th} (K/W)	t_i (s)
1	0.040	0.004
2	0.003	0.010
3	0.140	0.030
4	0.120	0.300
5	0.197	0.080

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Brake IGBT + Diode

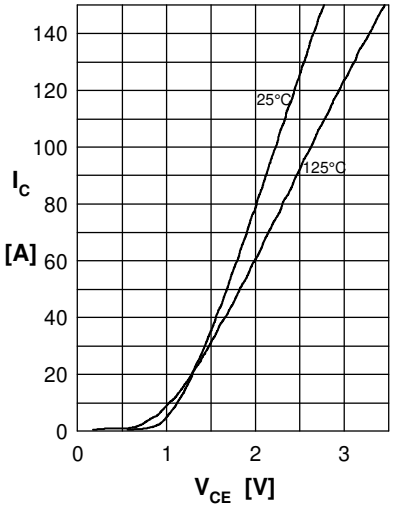


Fig.1 Output characteristics IGBT

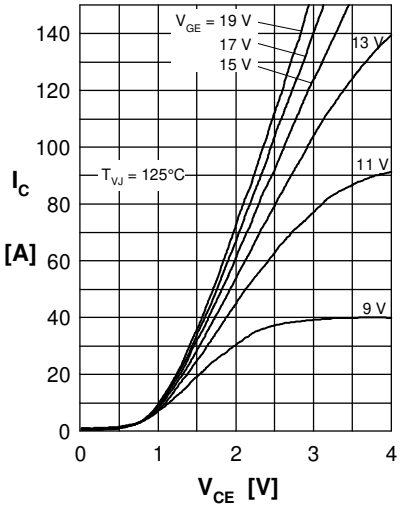


Fig.2 Typ. output characteristics IGBT

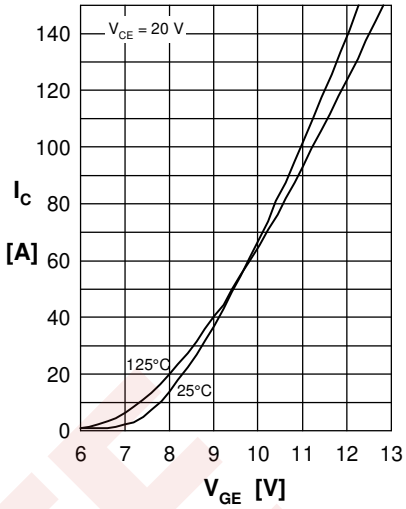


Fig. 3 Typ. transfer charact. IGBT

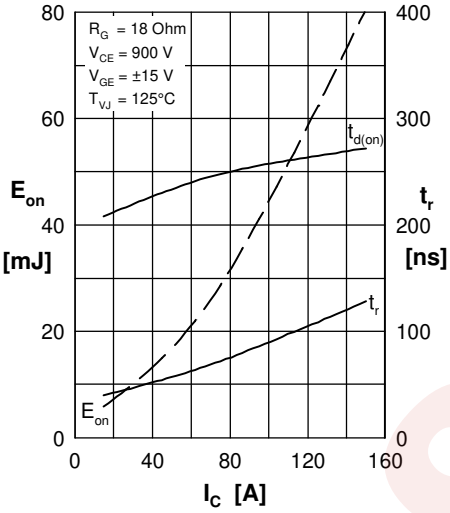


Fig. 4 Typ. turn-on energy & switch. times vs. collector current

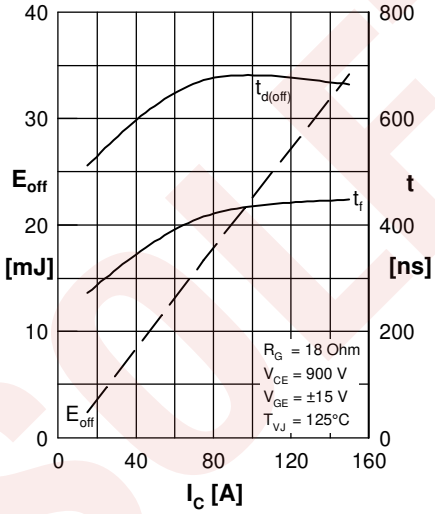


Fig. 5 Typ. turn-off energy & switch. times vs. collector current

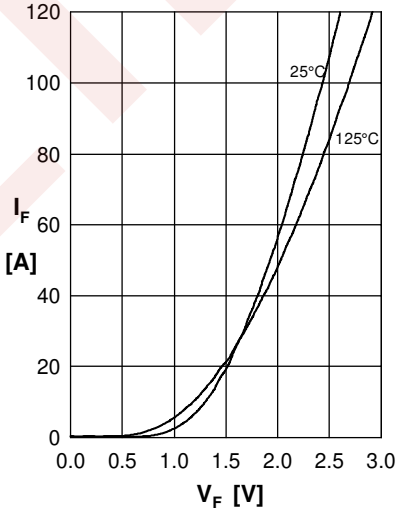


Fig. 6 Typ. forward characteristics Diode

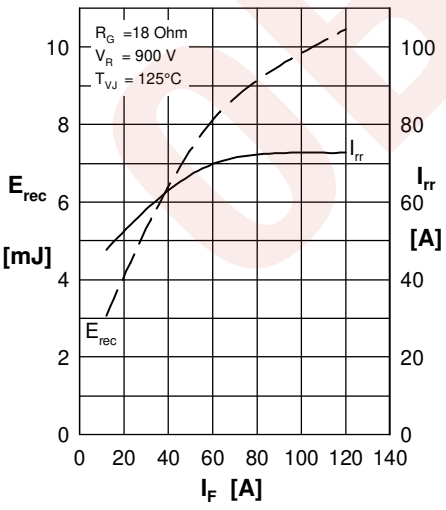


Fig. 7 Typ. reverse recovery characteristics Diode

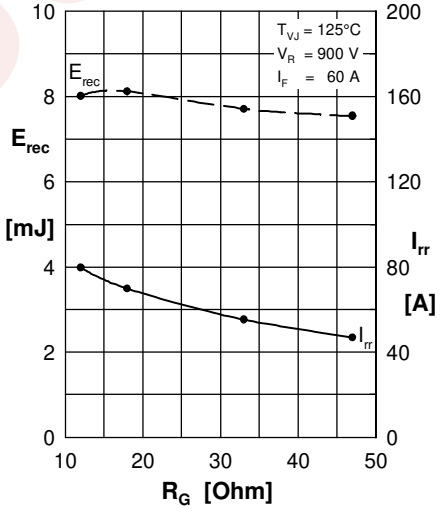


Fig. 8 Typ. reverse recovery characteristics Diode

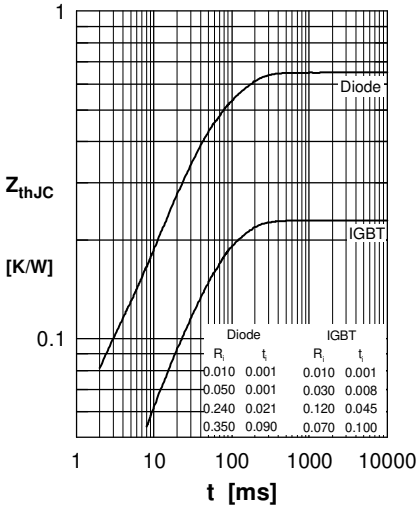


Fig. 9 Transient thermal resistance junction to case

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